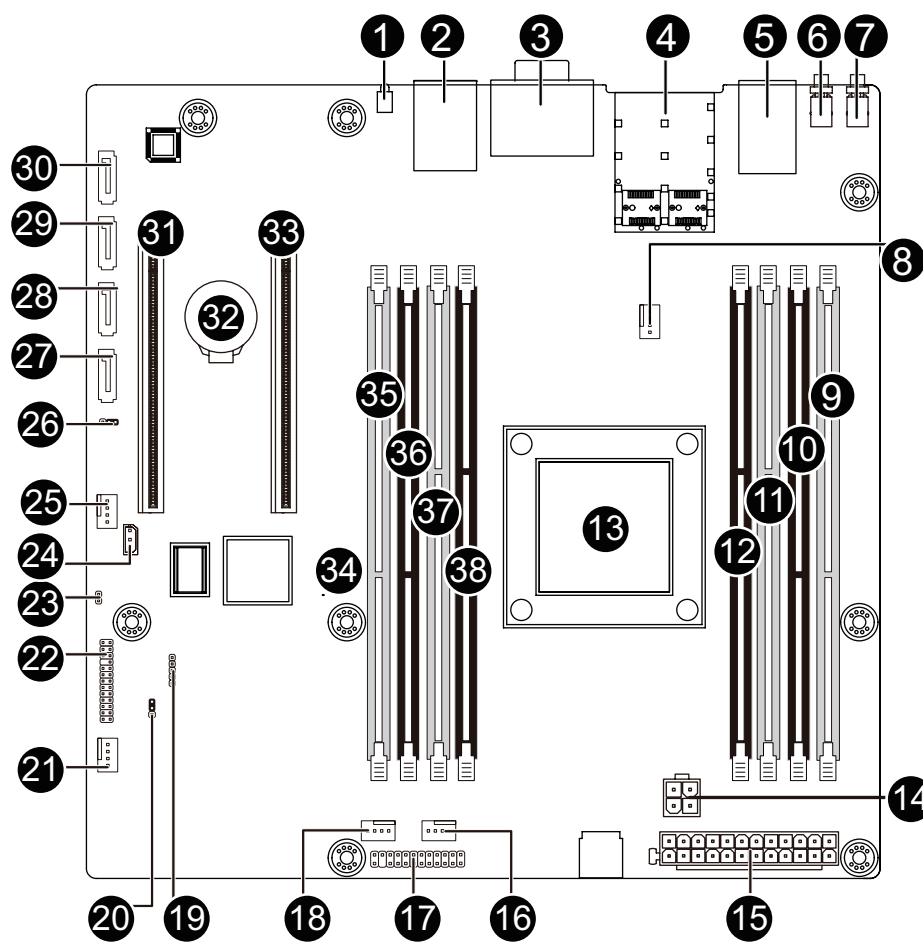


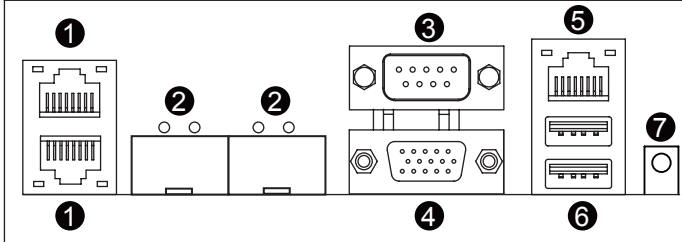
MP30-AR0/MP30-AR1 Quick Reference Guide/ 快速测试参考指南



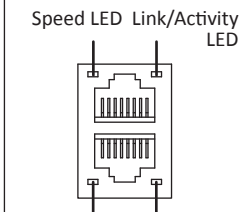
No.	Code	Description
1	LED_STA	System status LED
2	USB2_MLAN	KVM Server Management 10/100/1000 LAN port (top)/USB 2.0 ports (bottom)
3	VGA1_COM1	Serial port (top)/VGA port (bottom)
4	SFP+_1_2	SFP+ LAN port #1/#2
5	LAN1_2	GbE LAN port #1/#2
6	SW_PWR	Power/Reset button with LED
7	SW_ID	ID switch button with LED
8	CPU_FAN	CPU fan connector
9	DIMM_P0_A0	Channel 1 slot 0
10	DIMM_P0_A1	Channel 1 slot 1
11	DIMM_P0_B0	Channel 2 slot 0
12	DIMM_P0_B1	Channel 2 slot 1
13	CPU0	AppliedMicro® X-Genie 1 processor
14	P12V_AUX	14 pin power connector
15	ATX1	24 pin main power connector
16	SYS_FAN1	System fan connector#2
17	FP_1	Front panel header (for Server system)
18	SYS_FAN2	System fan connector#3
19	PMBUS	PMBus header
20	CLR_CMOS	Clear CMOS jumper

No.	Code	Description
21	SYS_FAN3	System fan connector#3
22	BP_1	HDD back plane board header
23	CASE_OPEN	Case open intrusion alert header
24	IPMB	IPMB connector
25	SYS_FAN4	System fan connector#4
26	SATA_DOM0	SATA port 1 DOM support jumper
27	SATA1	SATA 3 6Gb/s connector
28	SATA0	SATA 3 6Gb/s connector
29	SATA3	SATA 3 6Gb/s connector
30	SATA2	SATA 3 6Gb/s connector
31	PCI_E_2	PCI Express x16 slot (PCIe x8 Signal)
32	BAT	Battery socket
33	PCI_E_1	PCI Express x16 slot (PCIe x8 Signal)
34	LED_BMC	BMC firmware readiness LED
35	DIMM_P0_C0	Channel 3 slot 0
36	DIMM_P0_C1	Channel 3 slot 1
37	DIMM_P0_D0	Channel 4 slot 0
38	DIMM_P0_D1	Channel 4 slot 1

Rear I/O Connector/ 后面板接口



No.	Description
1	GbE LAN ports
2	SFP+ LAN ports
3	Serial port
4	VGA port
5	KVM Server Management 10/100/1000 LAN port (Dedicated LAN port)
6	USB 2.0 ports
7	System Status LED



10/100/1000 LAN LED:

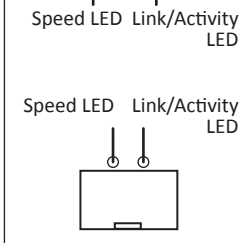
State	Description
Yellow On	1Gbps data arte
Green On	100Mbps data arte
Off	10Mbps data arte

System Status LED:

State	Description
Green On	System is operating normally.
Green Blink	Degrade condition, may indicates the following: • CPU failure • DIMM killed
Amber On	Critical condition, may indicates the following: • Power module failure • System fan failure • Power supply voltage issue • System temperature/voltage issue
Amber Blink	Non-critical condition, may indicates the following: • Redundant power module failure • Temperature and voltage issue • Chassis intrusion
N/A	System is not ready. May indicates the following: • POST error • NMI error • Processor or terminator missing

系统状态LED:

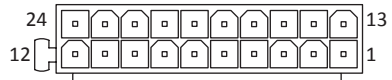
颜色/状态	说明
绿色恒亮	系统正常运行。
绿色闪烁	效能降低情形，可能为下列状况： 处理器问题 内存问题
橙色恒亮	严重情形，可能为下列状况： 电源模块故障 系统风扇故障 电源电压问题 系统温度/电压问题
橙色闪烁	非严重情形，可能为下列状况： 冗余电源模块故障 系统温度/电压问题 机箱侵入
无亮灯	系统未正常运行，可能为下列状况： POST错误 NMI错误 处理器或终结器缺失



SFP+ LAN LED:

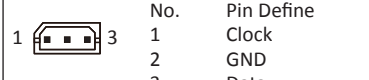
State	Description
Green On	10 Gbps data rate
Green Blink	Identify 10 Gbps data rate
Yellow On	1 Gbps data rate
Yellow Blink	Identify 1 Gbps data rate
Off	100 Mbps data rate

ATX Power/ 电源



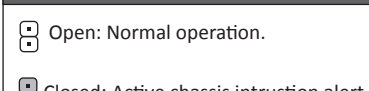
No.	Pin Define	No.	Pin Define
1	3.3V	13	3.3V
2	3.3V	14	-12V
3	GND	15	GND
4	+5V	16	PS_ON
5	GND	17	GND
6	+5V	18	GND
7	GND	19	GND
8	Power Good	20	-5V
9	5VSB	21	+5V
10	+12V	22	+5V
11	+12V	23	+5V
12	3.3V	24	GND

IPMB



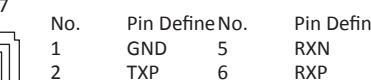
No.	Pin Define
1	Clock
2	GND
3	Data

CPU/System FAN/ 风扇



No.	Pin Define
1	GND
2	+12V
3	Sense
4	Speed Control

SATA Connector/SATA 接口



No.	Pin Define No.	Pin Define
1	GND	5 RXN
2	TXP	6 RXP
3	TXN	7 GND
4	GND	

BMC Firmware Readiness LED

State	Description
On	BMC firmware is initial
Blink	BMC firmware is ready
Off	AC loss

PMBUS

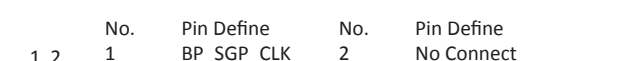
No.	Pin Define	No.	Pin Define
1	SMB CLK	4	GND
2	SMB DATA	5	3.3V
3	SMB ALERT		
5			

Front Panel Header/ 前面板



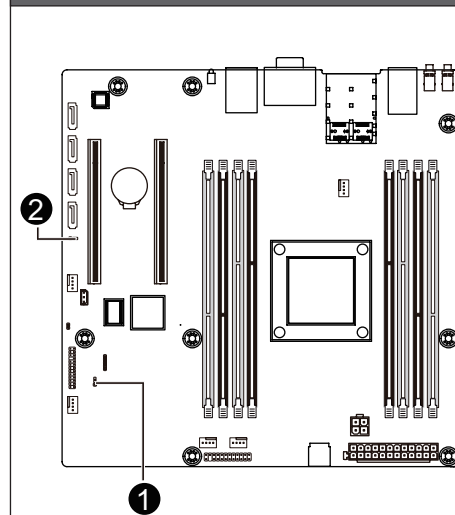
No.	Pin Define	No.	Pin Define
1	Power LED+	2	5V Standby
2	ID LED+	3	ID LED+
3	No Pin	4	ID LED-
4	Power LED-	5	ID LED-
5	HDD LED+	6	System Status LED+
6	HDD LED-	7	System Status LED-
7	Power Button	8	LAN1 Active LED+
8	GND	9	LAN1 Active LED-
9	Reset Button	10	SMBus Data
10	GND	11	SMBus Clock
11	ID Button	12	Case Open
12	GND	13	LAN2 Active LED
13	NMI Switch-	14	LAN2 Active LED-

HDD Back Plane Board Header/ 硬盘背板排针



No.	Pin Define	No.	Pin Define
1	BP_SGP_CLK	2	No Connect
2	BP_SGP_LOAD	3	FAN_Gate
3	BP_SGP_LOAD	4	GND
4	BP_SGP_LOAD	5	GND
5	BP_SGP_LOAD	6	Reset
6	BP_SGP_LOAD	7	BP_LED_A_N
7	BP_LED_G_N	8	GND
8	BP_LED_G_N	9	GND
9	BP_LED_G_N	10	No Connect
10	BP_LED_G_N	11	SMB_BP_DATA
11	BP_LED_G_N	12	SMB_BP_CLK
12	BP_LED_G_N	13	BMC_ACK
13	BP_LED_G_N	14	BMC_REQ
14	BP_LED_G_N	15	Key Pin
15	BP_LED_G_N	16	GND
16	BP_LED_G_N	17	GND
17	BP_LED_G_N	18	GND
18	BP_LED_G_N	19	P_3V3_AUX
19	BP_LED_G_N	20	P_3V3_AUX
20	BP_LED_G_N	21	GND
21	BP_LED_G_N	22	GND
22	BP_LED_G_N	23	GND
23	BP_LED_G_N	24	PRESENCE
24	BP_LED_G_N	25	GND
25	BP_LED_G_N	26	GND

Jumper Settings/ 跳线设置

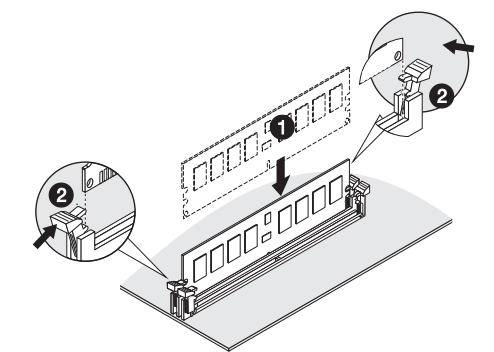


No.	Description
1	Clear CMOS Jumper 1-2 Close: Normal operation (Default setting) 2-3 Close: Clear CMOS data.
2	SATA Port 1 DOM Support Jumper 1-2 Close: Enable SATA port DOM support funtion. 2-3 Close: Normal Operation. (Default setting)

⚠ If a SATA type hard drive is connected to the motherboard, please ensure the jumper is closed and set to 2-3 pins (Default setting), in order to reduce any risk of hard disk damage.

Pin No.	Definition
1	P5V
2	SATA1 Pin7
3	GND

Memory Population Configuration/ 安装内存



Single DIMM per channel(1DPC) or Dual DIMMs per channel(2DPC) setting

1 Slot	2 Slot	4 Slot	8 Slot
1DPC	1DPC	2DPC	2DPC
A0 or C0	A0+B0 or A0+C0	A0+A1 or C0+C1	A0+B0 and C0+D0
	A0+A1+B0+B1 or A0+A1+C0+D0		Insert Full

Regulatory Notices

WEEE Symbol Statement



The symbol shown below is on the product or on its packaging, which indicates that this product must not be disposed of with other waste. Instead, the device should be taken to the waste collection centers for activation of the treatment, collection, recycling and disposal procedure. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment for recycling, please contact your local government office, your household waste disposal service or where you purchased the product for details of environmentally safe recycling.

- When your electrical or electronic equipment is no longer useful to you, "take it back" to your local or regional waste collection administration for recycling.
- If you need further assistance in recycling, reusing in your "end of life" product, you may contact us at the Customer Care number listed in your product's user's manual and we will be glad to help you with your effort.

Restriction of Hazardous Substances (RoHS) Directive Statement

GIGABYTE products have not intended to add and safe from hazardous substances (Cd, Pb, Hg, Cr+6, PBDE and PBB). The parts and components have been carefully selected to meet RoHS requirement. Moreover, we at GIGABYTE are continuing our efforts to develop products that do not use internationally banned toxic chemicals.

限制使用有害物质 (RoHS) 指令声明

GIGABYTE产品未故意添加和使用有害物质（Cd、Pb、Hg、Cr+6、PBDE和PBB）。所有部件和元件均经过严格挑选，符合RoHS要求。此外，我们GIGABYTE一直致力于开发不使用国际上禁止的有毒化学品的产品。

California Proposition 65 Warning

WARNING:

This product contains a chemicals , including lead, known to the State of California to cause cancer and birth defects or other reproductive harm. For more information, please visit: <http://www.p65warnings.ca.gov/>



Battery Warning:

Incorrectly installing a battery or using incompatible battery may increase the risk of ifre explosion. Replace the battery only with the same or equivalent type.

- Do not disassemble, crush, puncture batteries.
- Do not store or place your battery pack next to or in a heat source such as a fire, heatgenerating appliance, can or exhaust vent. Heating battery cells to temperatures above 65oC (149oF) can cause explosion or fire.
- Do not attempt to open or service batteries. Do not dispose of batteries in a fire or with household waste.



电池警告：

电池安装不当或使用不兼容的电池会增加火灾爆炸风险。更换电池时，只可使用相同或同等类型的电池。

- 请勿拆解、挤压、刺破电池。
- 请勿将电池存放或放置在热源中或旁边，如火源、产生热的设备、罐体或排气口。电池温度升至65oC (149oF)以上可能导致爆炸或火灾。
- 请勿尝试打开或维修电池。电池废弃时，请勿投入火中或者作为家庭废弃物进行处理。

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中华人民共和国电子信息产品中有毒有害物质或元素的名称及含量标识格式

依照中华人民共和国的有毒有害物质的限制要求(China RoHS)提供以下的表格：



关于符合中国《电子信息产品污染控制管理办法》的声明
Management Methods on Control of Pollution from Electronic Information Products
(China RoHS Declaration)

产品中有毒有害物质或元素的名称及含量
Hazardous Substances Table

部件名称(Parts)	有毒有害物质或元素(Hazardous Substances)					
	铅(Pb)	汞(Hg)	镉(Cd)	六价铬 (Or (VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
PCB板 PCB	○	○	○	○	○	○
结构件及风扇 Mechanical parts and Fan	×	○	○	○	○	○
芯片及其他主动零件 Chip and other Active components	×	○	○	○	○	○
连接器 Connectors	×	○	○	○	○	○
被动电子元器件 Passive Components	×	○	○	○	○	○
线材 Cables	○	○	○	○	○	○
焊接金属 Soldering metal	○	○	○	○	○	○
助焊剂、散热膏、标签及其他耗材 Flux, Solder Paste, Label and other Consumable Materials	○	○	○	○	○	○

○:表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006标准规定的限量要求以下。
Indicates that this hazardous substance contained in all homogenous materials of this part is below the limit requirement SJ/T 11363-2006

×:表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006标准规定的限量要求。
Indicates that this hazardous substance contained in at least one of the homogenous materials of this part is above the limit requirement in SJ/T 11363-2006

对销售之日的所发售产品，本表显示我公司供应链的电子信息产品可能包含这些物质。注意：在所售产品中可能会也可能不会含有所有列出的部件。
This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of the sale of the enclosed products. Note that some of the component types listed above may or may not be a part of the enclosed product.